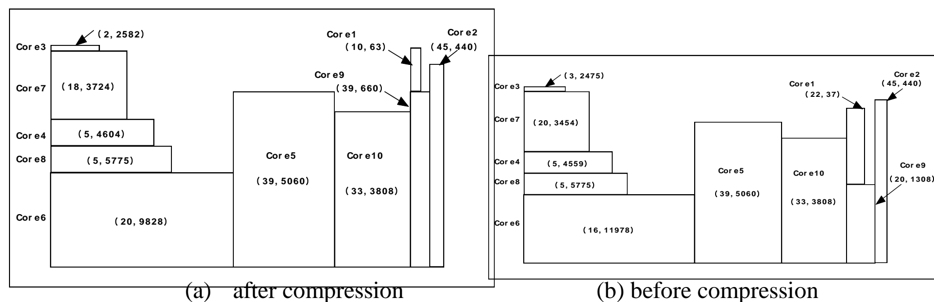
4 Conclusions

We perform the following experiment to illustrate the effectiveness of the compression process to reduce the test time: Set the maximum width of 50, the highest temperature of 98.2 ℃，Design result of d695 in ITC 02 standard circuit is shown in figure 3.The figure (a) shoes the case by use of the compression process, and the figure (b) is the case before compression process. The testing time is 19796 in figure (a) and 22594 in figure (b) educes 2798 after compression process. The total testing time reduced by 12.4%.



(a) after compression (b) before compression

Fig. 3. The effect of compression

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